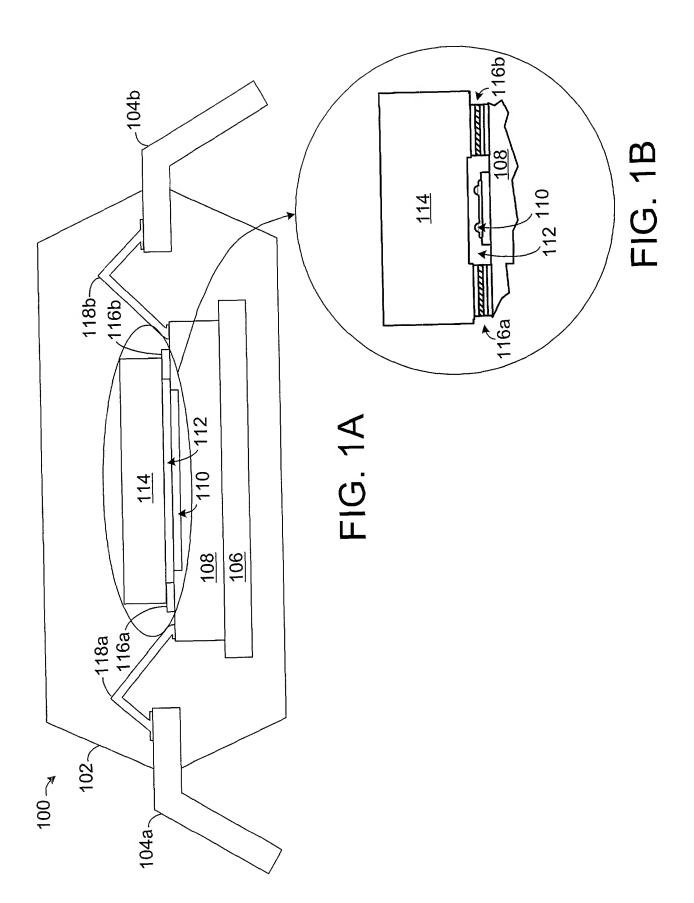
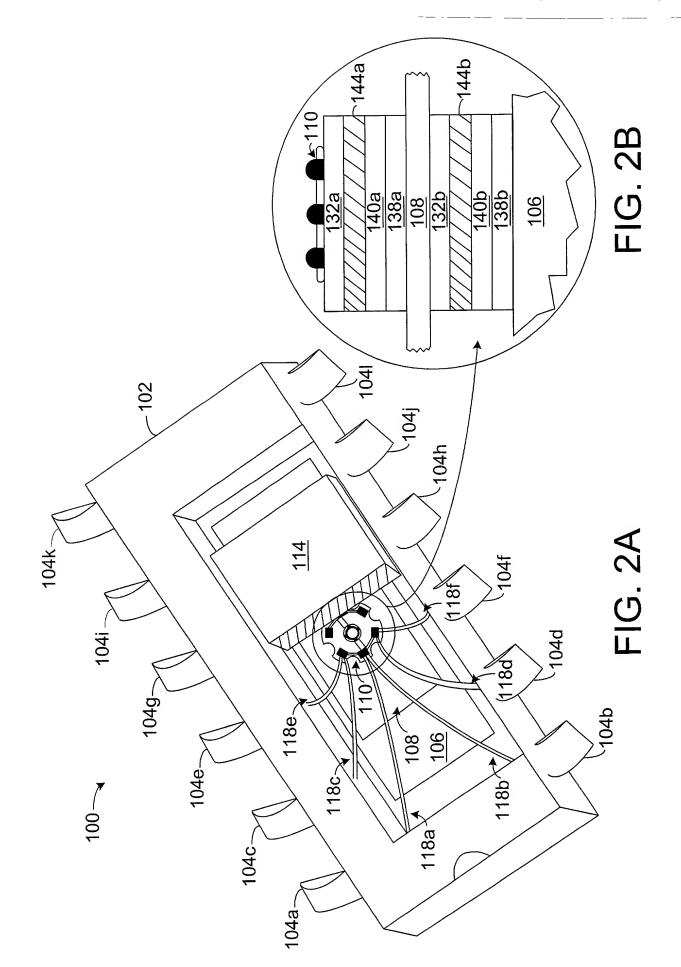
Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

Based Devices

Honeywell Case No H0002988, Docket 01-1612

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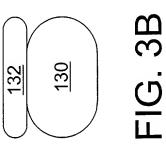


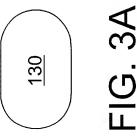
Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS
Paged Devices.

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FIG. 3C 130 134 132





Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS
Based Devices
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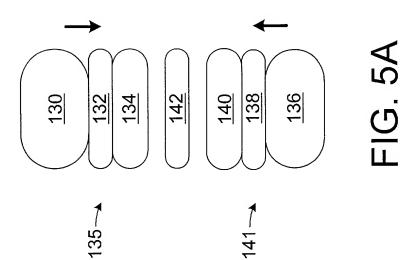
FIG. 4B

Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

Based Devices

Honeywell Case No H0002988, Docket. 01-1612

130 138 136 132 140



no otherwise

140 Au Diffusion of Au Diffusion of In atoms → ← atoms 144 FIG. 6B 142 드 Diffusion of In Diffusion of Au atoms → ← atoms 144 134 Au Au 140 FIG. 6A In 142 Au 134

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142

Based Devices

Honeywell Case No. H0002988, Docket

FIG. 7A

FIG. 7B

Inventor: William P. Platt
Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

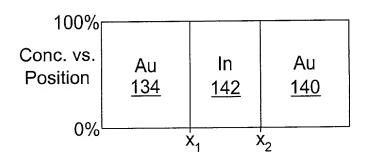


FIG. 8A

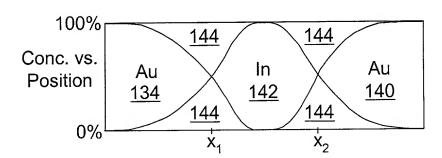


FIG. 8B

			1
142	<u>2</u> "1/3	In"	144
134	<u>4</u> "2/3	Au"	<i>\</i>

FIG. 8C

Title: Bonding for a Micro-Electro-Mechanical System (MEMS) and MEMS

Honeywell Case No H0002988, Docket 01-1612



FIG. 9

